

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

1. (currently amended) A transferring apparatus provided between ~~a plurality of~~ first and second carrying apparatuses, each carrying apparatus comprising:

a plurality of wafer mounts, each wafer mount having support means for supporting ~~carried products~~ a single wafer,

a guide rail means for controlling the ~~a~~ moving direction of the ~~support means~~ plurality of wafer mounts, the guide rail means being provided along adjacent to a plurality of processing apparatus apparatuses for processing ~~the carried products~~ wafers, the plurality of processing apparatuses being arranged along the moving direction of the plurality of wafer mounts, and

a drive unit ~~moving means~~ for moving the ~~support means~~ plurality of wafer mounts along the guide rail means,

the transferring apparatus including:

a synchronization control unit means for synchronizing a first drive unit of the first carrying apparatus with a second drive unit of the second carrying apparatus ~~the moving means of one carrying apparatus with the moving means of another carrying apparatus;~~ and

at least one ~~hand-over means~~ transfer robot for receiving transferring wafers from the plurality of wafer mounts of the first ~~the carried products from the support means of the one carrying apparatus and handing over the carried products to~~

the plurality of wafer mounts of the second ~~support means of the other~~ carrying apparatus according to a drive control signal from the synchronization unit, the drive control signal corresponding to the synchronization between the first and second drive units.

2. (currently amended) The transferring apparatus according to claim 1,
wherein the at least one transfer robot transfers ~~hand-over means receives~~ some ~~carried products~~ wafers selected among the a plurality of wafers ~~the carried products~~ which are carried by the ~~one~~ first carrying apparatus.

3. (currently amended) The transferring apparatus according to claim 1,
wherein the at least one transfer robot transfers ~~hand-over means receives~~ all the wafers ~~carried products~~ which are carried by the ~~one~~ first carrying apparatus.

4. (currently amended) The transferring apparatus according to claim 1,
further comprising at least one buffer means for temporarily storing the ~~carried products~~ wafers between the ~~one~~ first carrying apparatus and the ~~other~~ second carrying apparatus.

5. (withdrawn) The transferring apparatus according to claim 4,
wherein the transferring apparatus is integrated with each of the carrying apparatuses.

6. (currently amended) The transferring apparatus according to claim 5, wherein each of the ~~carried products~~ wafers comprises a substrate wafer.
7. (withdrawn) The transferring apparatus according to claim 6, wherein the substrate wafer comprises a semiconductor wafer.
8. (currently amended) The transferring apparatus according to claim 5, wherein each of the ~~carried products~~ wafers comprises an electronic device manufacturing substrate.
9. (withdrawn) The transferring apparatus according to claim 8, wherein the electronic device manufacturing substrate comprises a liquid crystal device substrate.
10. (withdrawn) The transferring apparatus according to claim 8, wherein the electronic device manufacturing substrate comprises a quartz device substrate.
11. (currently amended) The transferring apparatus according to claim 4, wherein each of the buffer means is provided in combination with each of the ~~hand-over means~~ transfer robot.
12. (currently amended) The transferring apparatus according to the claim 4,

wherein the buffer means is shared by the at least one transfer robot ~~plurality of the hand-over means.~~

13. (currently amended) The transferring apparatus according to claim 1,
wherein each of ~~the carried products~~ wafer comprises a substrate wafer.
14. (original) The transferring apparatus according to claim 13,
wherein the substrate wafer comprises a semiconductor wafer.
15. (currently amended) The transferring apparatus according to claim 1,
wherein each of ~~the carried products~~ wafer comprises an electronic device
manufacturing substrate.
16. (original) The transferring apparatus according to claim 15,
wherein the electronic device manufacturing substrate comprises a liquid crystal
device substrate.
17. (original) The transferring apparatus according to claim 15,
wherein the electronic device manufacturing substrate comprises a quartz device
substrate.
18. (original) The transferring apparatus according to claim 1,

wherein the transferring apparatus is integrated with each of the carrying apparatuses.

19. (currently amended) The transferring apparatus according to claim 18,
wherein each of the ~~carried products~~ wafer comprises a substrate wafer.
20. (original) The transferring apparatus according to claim 19,
wherein the substrate wafer comprises a semiconductor wafer.
21. (currently amended) The transferring apparatus according to claim 18,
wherein each of the ~~carried products~~ wafer comprises an electronic device manufacturing substrate.
22. (original) The transferring apparatus according to claim 21,
wherein the electronic device manufacturing substrate comprises a liquid crystal device substrate.
23. (original) The transferring apparatus according to claim 21,
wherein the electronic device manufacturing substrate comprises a quartz device substrate.
24. (cancelled)
25. (cancelled).

26. (cancelled)
27. (cancelled)
28. (cancelled)
29. (cancelled)
30. (cancelled)
31. (cancelled)
32. (cancelled)
33. (cancelled)
34. (cancelled)
35. (cancelled)
36. (cancelled)
37. cancelled)
38. (cancelled)
39. (cancelled)
40. (withdrawn)
41. (cancelled)
42. (cancelled)
43. (cancelled)
44. (cancelled)
45. (cancelled)
46. (cancelled)
47. (currently amended) A transferring method being performed between a plurality of carrying apparatuses, each carrying apparatus comprising:

a plurality of wafer mounts, each wafer mount having support means for supporting ~~carried products~~ a single wafer;

a guide rail means for controlling the a moving direction of the plurality of wafer mounts support means, the guide rail means being provided along adjacent to a plurality of processing apparatuses apparatus for processing wafers, the carried products the plurality of processing apparatuses being arranged along the moving direction of the plurality of wafer mounts; and

a drive unit moving means for moving the plurality of wafer mounts support means along the guide rail means,

wherein, while the drive unit moving means of one carrying apparatus is synchronized with the drive unit moving means of another carrying apparatus, the ~~carried products~~ wafers are received from the plurality of wafer mounts support means of the one carrying apparatus and handed over to the plurality of wafer mounts support means of the other carrying apparatus according to the synchronization.